



KESTER® 268 FLUX-CORED WIRE

Zero-Halogen, No-Clean Cored Wire for Robotic & Manual Soldering

DESCRIPTION

Kester 268 Flux-Cored Wire is a zero-halogen wire optimized for robotic soldering applications. With its unique chemistry system, Kester 268 provides consistent workability performance for both robotic and manual soldering in the electronics industry, with performance equivalent to conventional halogen/ halide-based systems. Kester 268 provides a clean release which prevents occurrences of bridges and protrusions, even in narrow-pitch automated drag soldering. The use of Kester 268 results in a clear post-soldering residue without the need for cleaning. Kester 268 is classified as Type ROL0 flux under J-STD-004B specifications. Kester 268 is zero-halogen and halide-free with no intentional addition of bromine and chlorine, conforming to the strictest requirements of IEC 61249-2-21, JPCA-ES-01 and IPC-410B specifications. For a list of compatible products contact MacDermid Alpha Technical Support.

READ ENTIRE TECHNICAL DATA SHEET BEFORE USING THIS PRODUCT

FEATURES & BENEFITS

- Low occurrence of solder ball spatter
- Conforms to halogen-free requirement of IEC 61249-2-21, JPCA-ES-01 and IPC-410B specifications with no intentionally added halogens and halides
- Low smoke and odor
- Excellent wetting speed and spread; superior to halogenated materials
- Clear residue, resulting in excellent joint aesthetics after soldering
- Excellent surface wettability and spreading suitable for robotic soldering and manual soldering
- Excellent manufacturing consistency and uniform quality, minimizes defects for all types of soldering
- Classified as ROL0 per J-STD-004B

ROHS COMPLIANCE

This product meets the requirements of the RoHS (Restriction of Hazardous Substances) Directive, 2002/95/EC Article 4 for the stated banned substances. (Applies only if this core flux is combined with a lead-free alloy.)





TECHNICAL DATA SHEET

TECHNICAL DATA

Category	Results	Procedure/Remarks
Reliability Properties		
Copper Mirror Corrosion	Low	Tested to J-STD-004B, IPC-TM-650, Method 2.3.32
Corrosion Test	Low	Tested to J-STD-004B, IPC-TM-650, Method 2.6.15
Silver Chromate	Pass	Tested to J-STD-004B, IPC-TM-650, Method 2.3.33
Quantitative Halides	None Detected	Tested to J-STD-004, IPC-TM-650, Method 2.3.28.1
Quantitative Halogens	None Detected	Tested to IPC-TM-650, Method 2.3.35, JPCS- ES-01, prEN14582 and IEC 61189-2 Test 2C12 specifications
Surface Insulation Resistance (SIR) 40 °C/90% RH, IPC (Typical)	Pass	Tested to J-STD-004B, IPC-TM-650, Method 2.6.3.7

PROCESSING GUIDELINES

Solder iron tip temperatures are most commonly between 371 to 400 °C (700 to 750 °F) for lead-free alloys and 315 to 343 °C (600 to 650 °F) for leaded alloys. Heat both the land area and component lead to be soldered with the iron tip prior to applying the solder wire to land area or component lead. To maximize tip life and reduce solder spattering, do not feed wire directly to iron tip.

Additional liquid flux should only be used as a last resort. Any flux applied to the solder location should be kept to the area of the connection being reworked. If needed, Kester NF372-TB may be used as a compatible liquid flux to aid in enhancing solderability of soldered joints. NF372-TB is also available in as a Flux-Pen® for optimum board cleanliness.

Cleaning

Kester 268 possesses excellent fluxing ability. The flux residues are non-corrosive, non-conductive, and do not require removal for most applications under normal conditions of use. IPA will not clean the residues off the surface of the circuit board after the soldering process. If removal is required, a saponifier or cleaning agent specifically designed to clean a no-clean flux





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is required to clean the residues. Please contact MacDermid Alpha Technical Support for further information.

Storage, Handling and Shelf Life

Storage must be in a dry, non-corrosive environment between 10 to 40 °C (50 to 104 °F). The surface may lose its shine and appear a dull shade of grey. This is a surface phenomenon and is not detrimental to product functionality. Flux-cored solder wire has a shelf life determined by the alloy used in the wire. For alloys containing more than 70% lead, the shelf life is 2 years from the date of manufacture. Other alloys have a shelf life of 3 years from the date of manufacture.

AVAILABILITY

Kester 268 is available in SAC305 and K100LD lead-free alloys, as well as Sn63Pb37 with 3.3% flux, and up to 4.4% flux in SAC305 for additional solderability where required. For low-cost, lead-free soldering applications, the K100LD alloy is ideal. Wire diameters typically range from 0.25 to 1.6 mm (0.010 to 0.063 in).

RECYCLING SERVICES

We provide safe and efficient recycling services to help companies meet their environmental and legislative requirements and at the same time, maximize the value of their waste streams.

Our service collects solder dross, solder scrap, and various forms of solder paste waste. Please contact your local sales representative for recycling capabilities in your area.





Technical Data Sheet Issue: 06 June 2025



TECHNICAL DATA SHEET

SAFETY & WARNING

It is recommended that the company/operator read and review the Safety Data Sheets for the appropriate health and safety warnings before use. **Safety Data Sheets are available.**

CONTACT INFORMATION

www.macdermidalpha.com

North America 140 Centennial Avenue Piscataway, NJ 08854 1.800.367.5460

EuropeUnit 2, Genesis Business Park
Albert Drive
Woking, Surrey, GU21 5RW, UK
44.01483.758400

Asia 8/F., Two Sky Parc 51 Hung To Road Kwun Tong, Kowloon, Hong Kong, SAR China 852.2500.5365

Also read carefully warning and safety information on the Safety Data Sheet. This data sheet contains technical information required for safe and economical operation of this product. READ IT THOROUGHLY PRIOR TO PRODUCT USE. Emergency safety directory assistance: US 1 202 464 2554, Europe + 44 1235 239 670, Asia + 65 3158 1074, Brazil 0800 707 7022 and 0800 172 202, Mexico 01800 002 1400 and (55) 5559 1588

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